

2SJ506(L), 2SJ506(S)

Silicon P Channel MOS FET
High Speed Power Switching

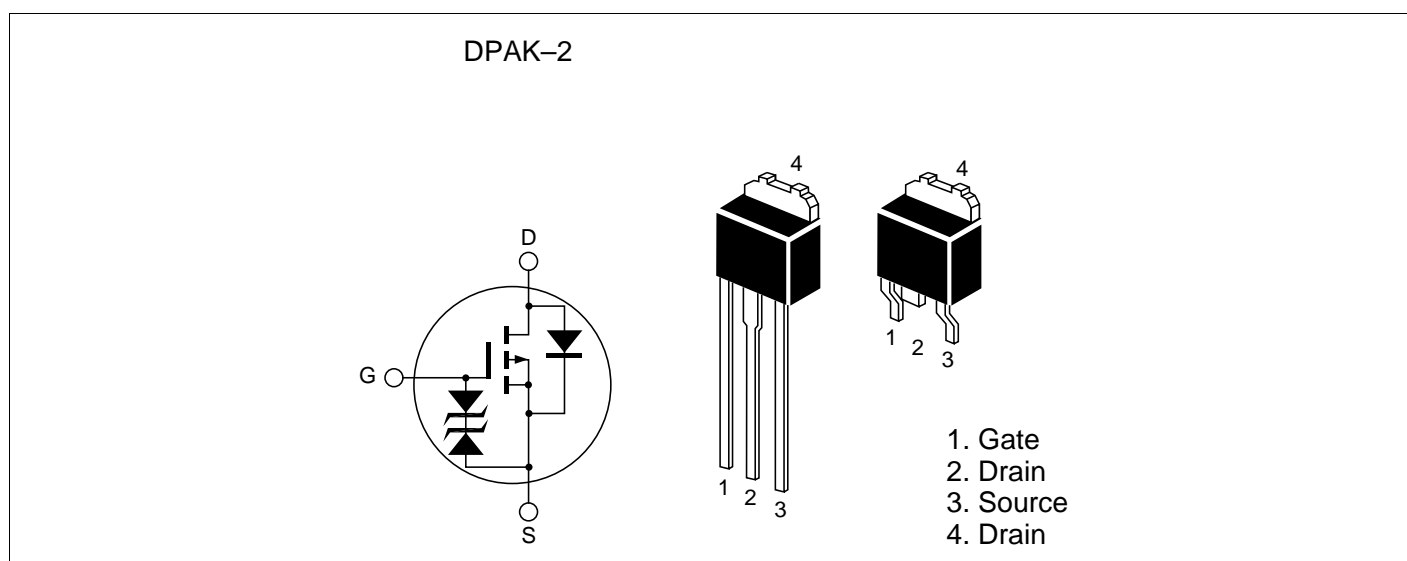
HITACHI

ADE-208-548
Target Specification 1st. Edition

Features

- Low on-resistance
 $R_{DS(on)} = 0.065 \Omega$ typ. (at $V_{GS} = -10V$, $I_D = -5A$)
- Low drive current
- High speed switching
- 4V gate drive devices.

Outline



2SJ506(L), 2SJ506(S)

Absolute Maximum Ratings (Ta = 25°C)

| Item | Symbol | Ratings | Unit |
|---|---------------------------------|-------------|------|
| Drain to source voltage | V_{DSS} | -30 | V |
| Gate to source voltage | V_{GSS} | ± 20 | V |
| Drain current | I_D | -10 | A |
| Drain peak current | $I_{D(pulse)}$ ^{Note1} | -40 | A |
| Body to drain diode reverse drain current | I_{DR} | -10 | A |
| Channel dissipation | P_{ch} ^{Note2} | 20 | W |
| Channel temperature | T_{ch} | 150 | °C |
| Storage temperature | T_{stg} | -55 to +150 | °C |

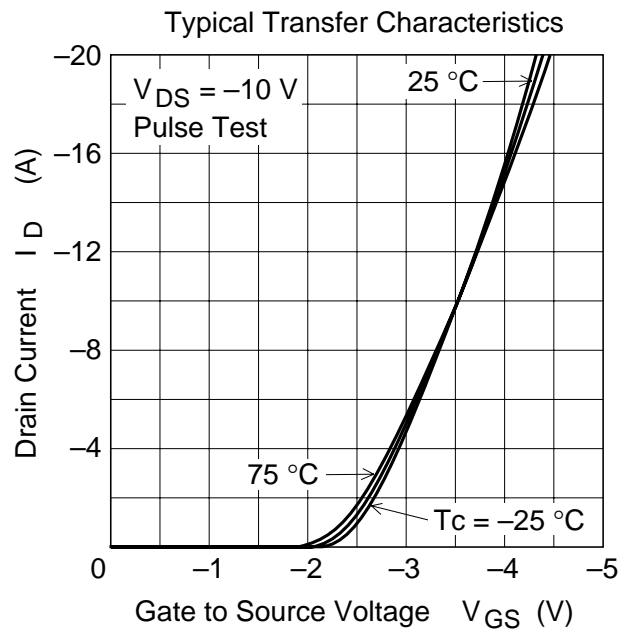
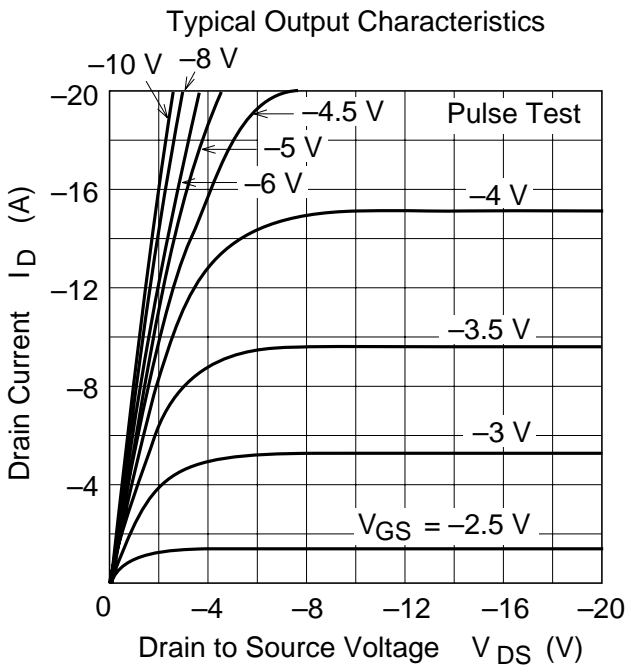
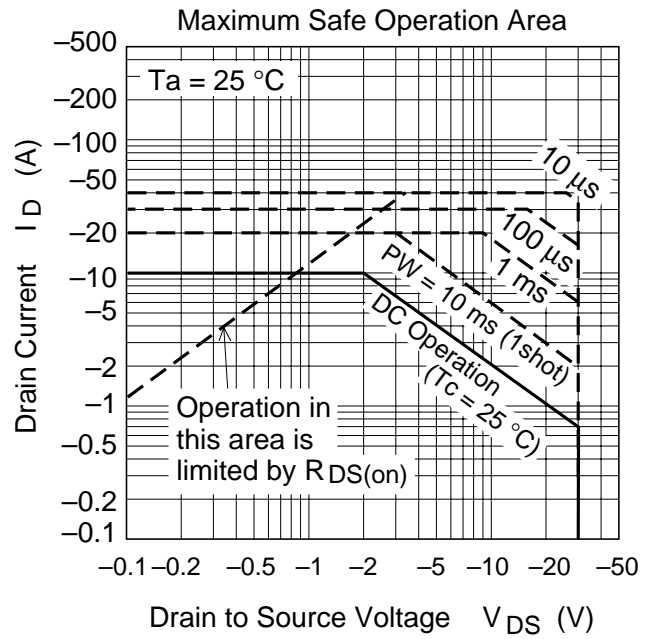
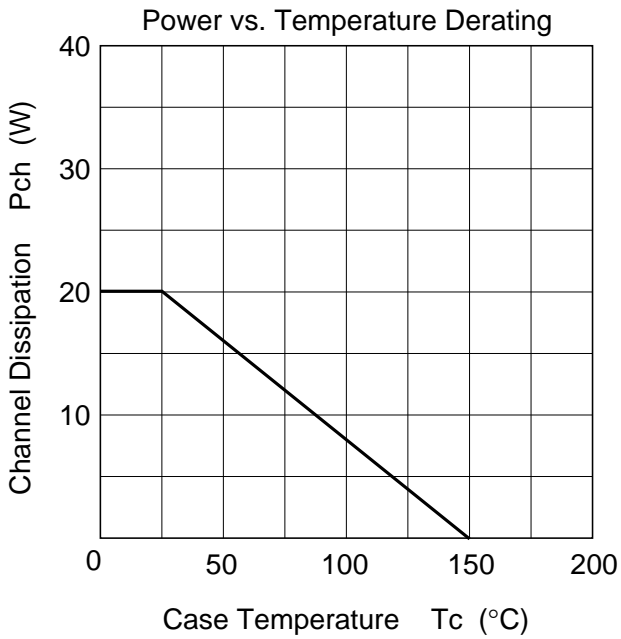
Notes: 1. $PW \leq 10\mu s$, duty cycle $\leq 1\%$
2. Value at $T_c = 25^\circ C$

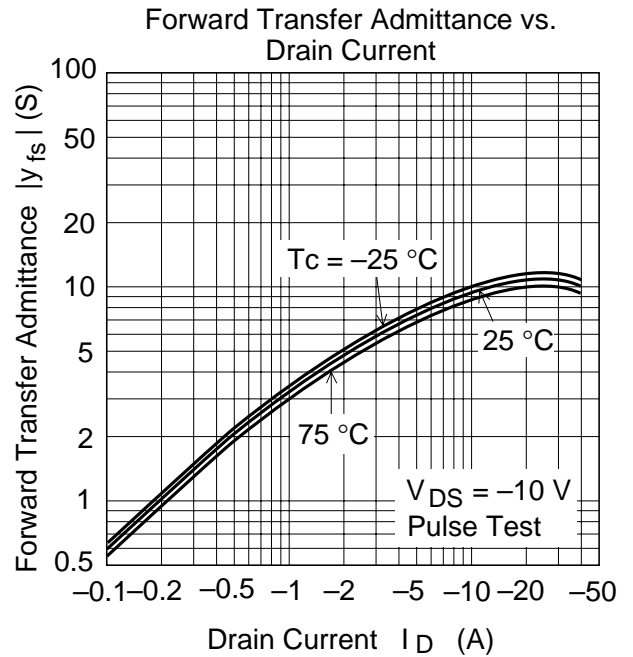
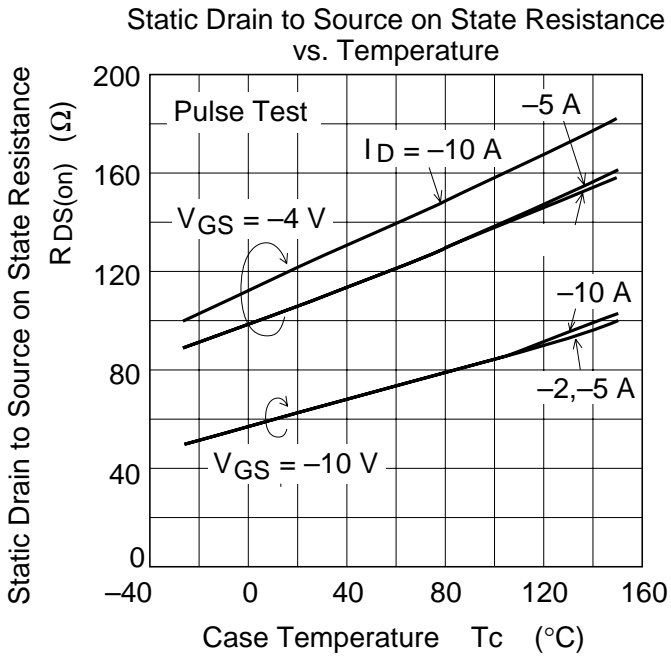
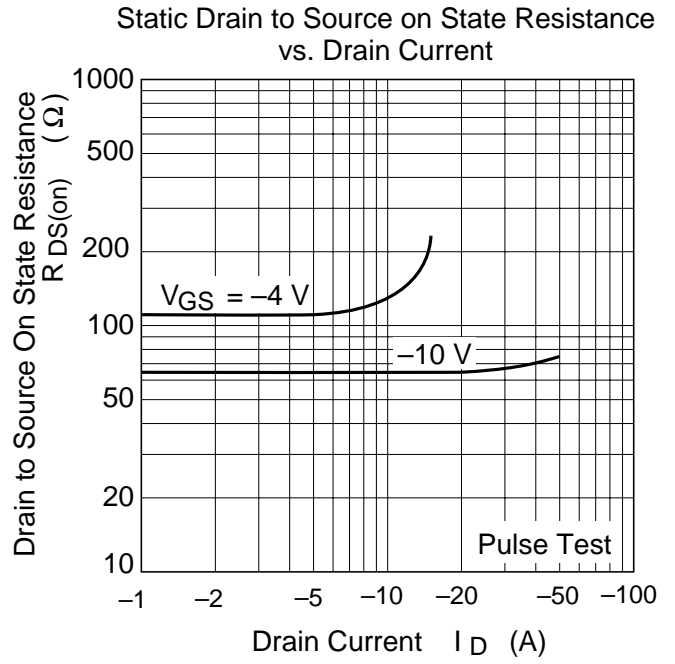
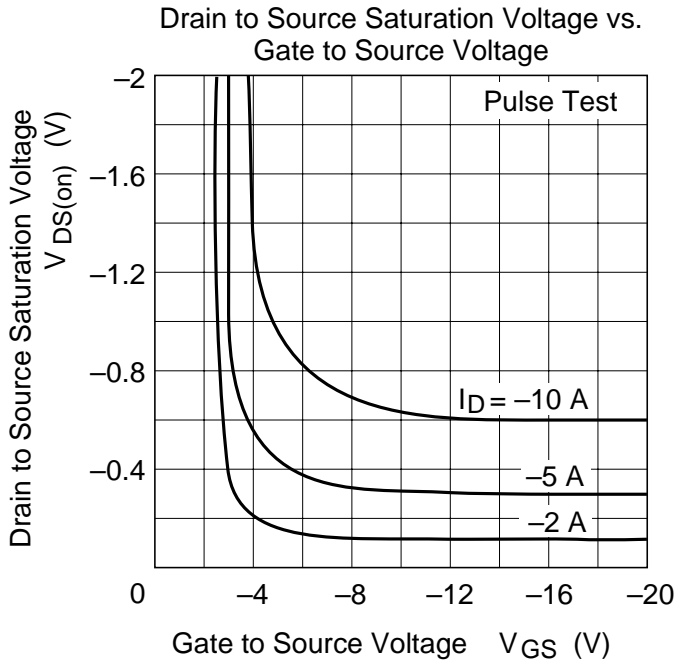
Electrical Characteristics (Ta = 25°C)

| Item | Symbol | Min | Typ | Max | Unit | Test Conditions |
|--|---------------|----------|-------|----------|---------------|---|
| Drain to source breakdown voltage | $V_{(BR)DSS}$ | -30 | — | — | V | $I_D = -10\text{mA}, V_{GS} = 0$ |
| Gate to source breakdown voltage | $V_{(BR)GSS}$ | ± 20 | — | — | V | $I_G = \pm 100\mu\text{A}, V_{DS} = 0$ |
| Zero gate voltage drain current | I_{DSS} | — | — | -10 | μA | $V_{DS} = -30\text{V}, V_{GS} = 0$ |
| Gate to source leak current | I_{GSS} | — | — | ± 10 | μA | $V_{GS} = \pm 16\text{V}, V_{DS} = 0$ |
| Gate to source cutoff voltage | $V_{GS(off)}$ | -1.0 | — | -2.0 | V | $I_D = -1\text{mA}, V_{DS} = -10\text{V}$ |
| Static drain to source on state resistance | $R_{DS(on)}$ | — | 65 | 85 | m Ω | $I_D = -5\text{A}, V_{GS} = -10\text{V}^{\text{Note3}}$ |
| | $R_{DS(on)}$ | — | 110 | 180 | m Ω | $I_D = -5\text{A}, V_{GS} = -4\text{V}^{\text{Note3}}$ |
| Forward transfer admittance | $ y_{fs} $ | 10 | 16 | — | S | $I_D = -5\text{A}, V_{DS} = -10\text{V}^{\text{Note3}}$ |
| Input capacitance | C_{iss} | — | 660 | — | pF | $V_{DS} = -10\text{V}$ |
| Output capacitance | C_{oss} | — | 440 | — | pF | $V_{GS} = 0$ |
| Reverse transfer capacitance | C_{rss} | — | 140 | — | pF | $f = 1\text{MHz}$ |
| Turn-on delay time | $t_{d(on)}$ | — | 12 | — | ns | $I_D = -5\text{A}, R_L = 2\Omega$ |
| Rise time | t_r | — | 65 | — | ns | $V_{GS} = -10\text{V}$ |
| Turn-off delay time | $t_{d(off)}$ | — | 85 | — | ns | |
| Fall time | t_f | — | 65 | — | ns | |
| Body to drain diode forward voltage | V_{DF} | — | -1.05 | — | V | $I_F = -10\text{A}, V_{GS} = 0$ |
| Body to drain diode reverse recovery time | t_{rr} | — | 65 | — | ns | $I_F = -10\text{A}, V_{GS} = 0$ $di_F/dt = 50\text{A}/\mu\text{s}$ |

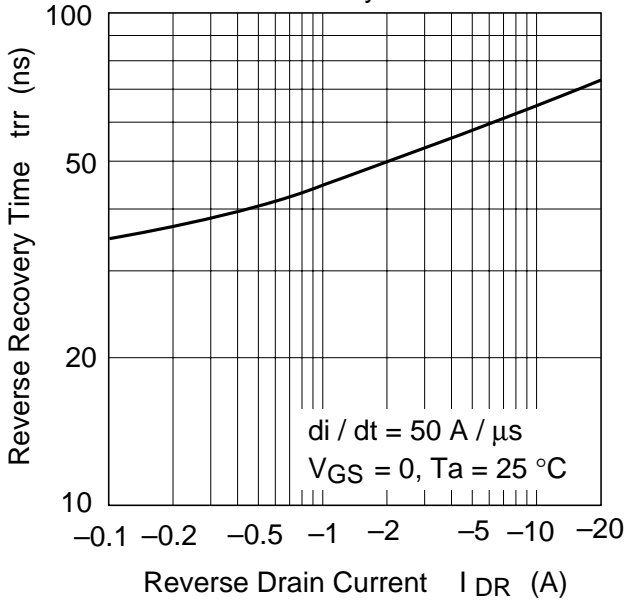
Note: 3. Pulse test

Main Characteristics

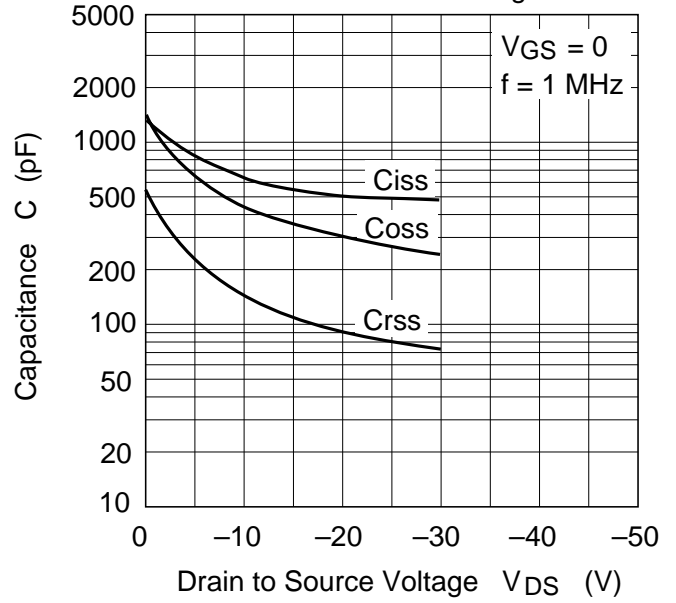




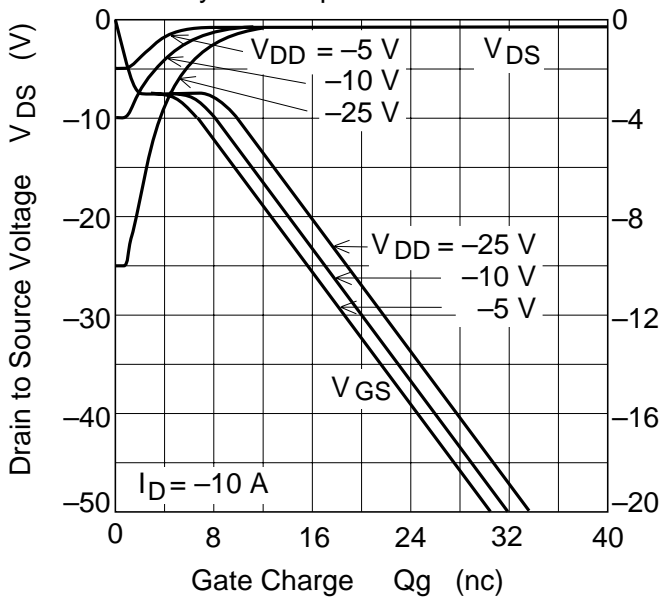
Body to Drain Diode Reverse Recovery Time



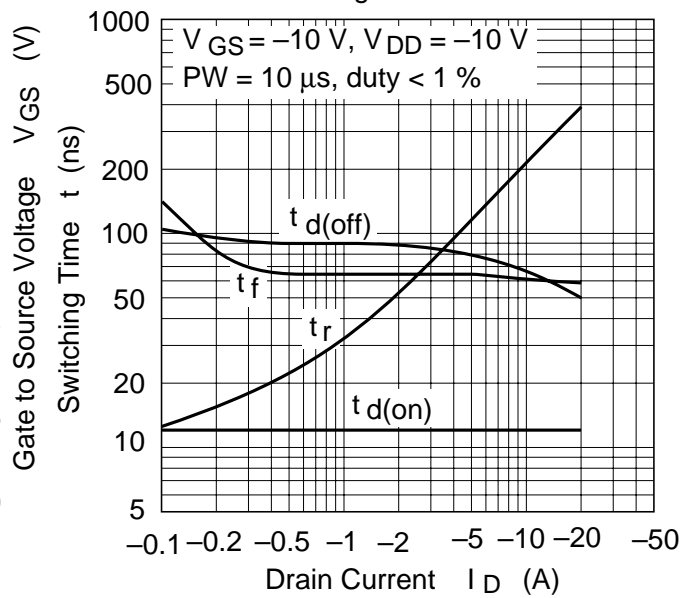
Typical Capacitance vs. Drain to Source Voltage

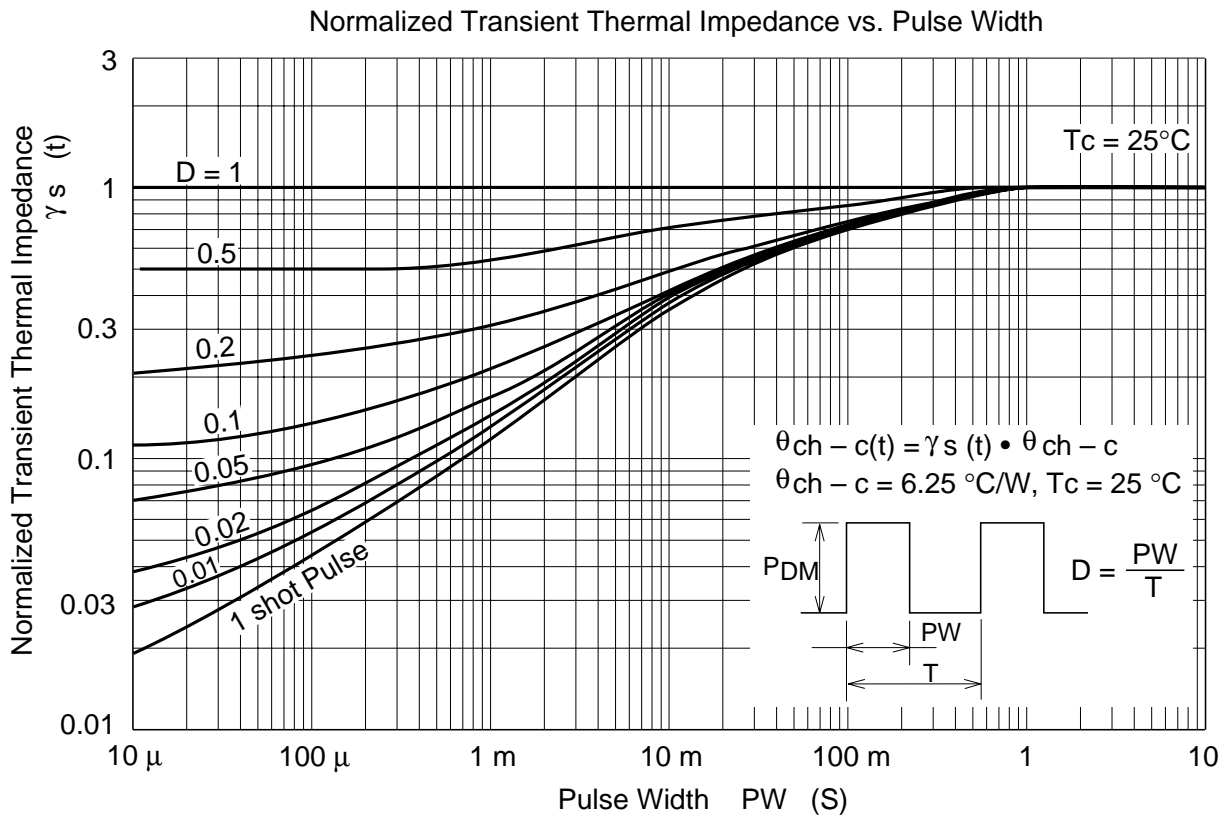
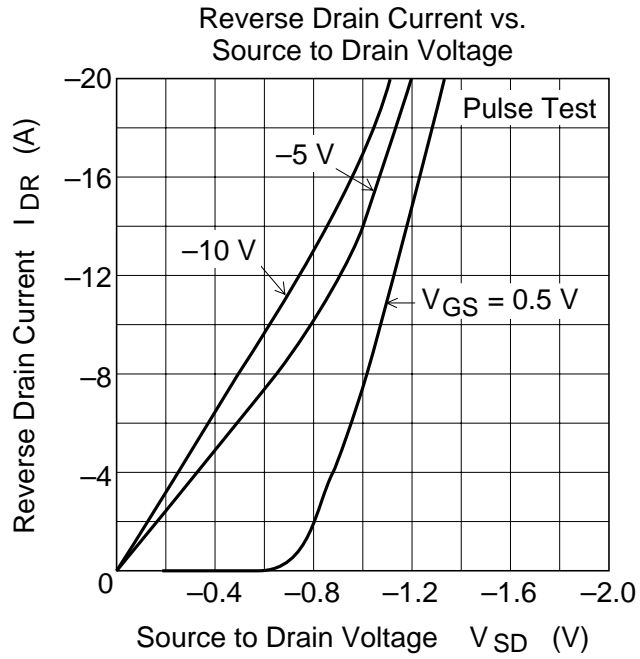


Dynamic Input Characteristics

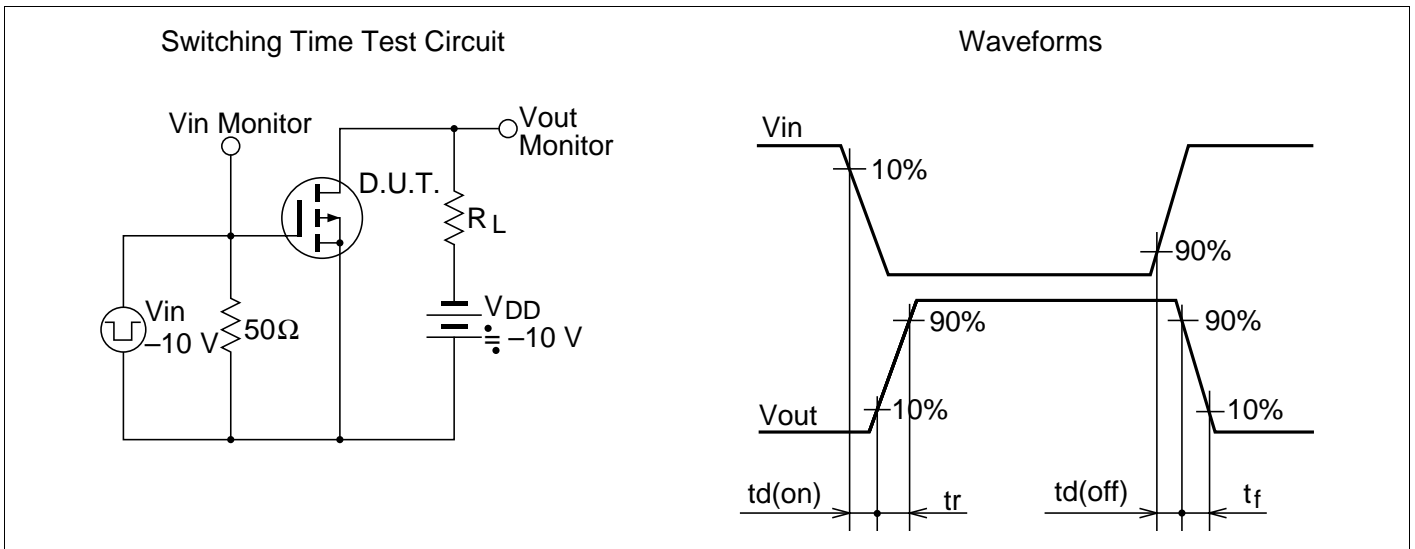


Switching Characteristics



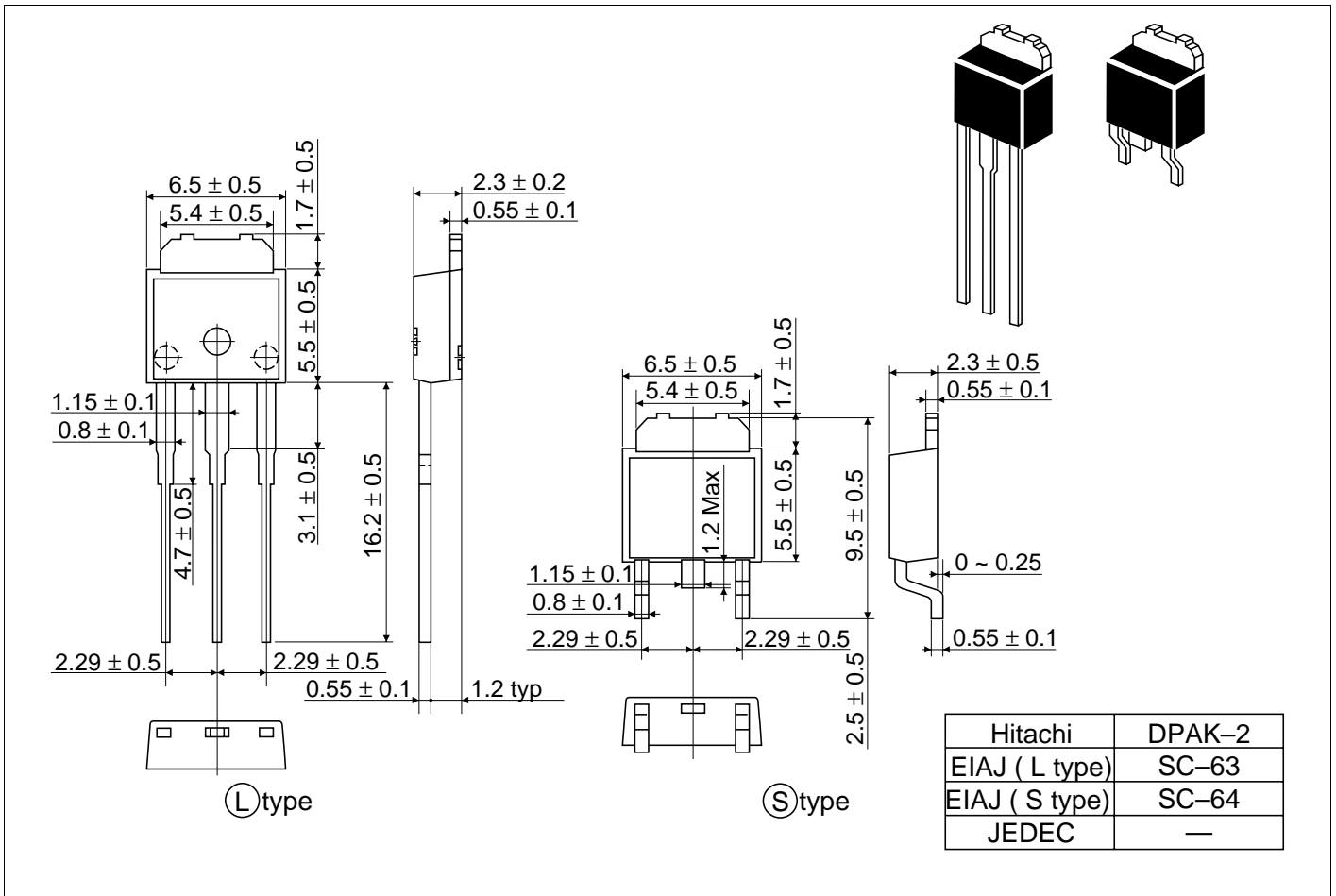


2SJ506(L), 2SJ506(S)



Package Dimensions

Unit: mm



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